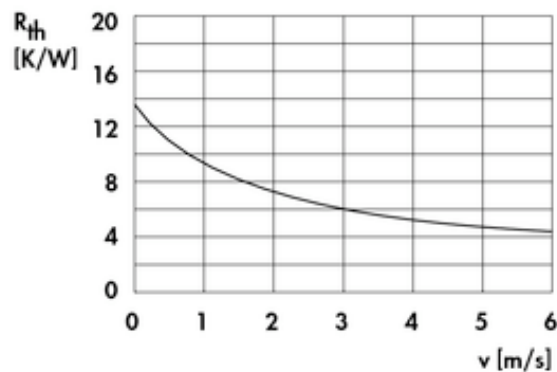
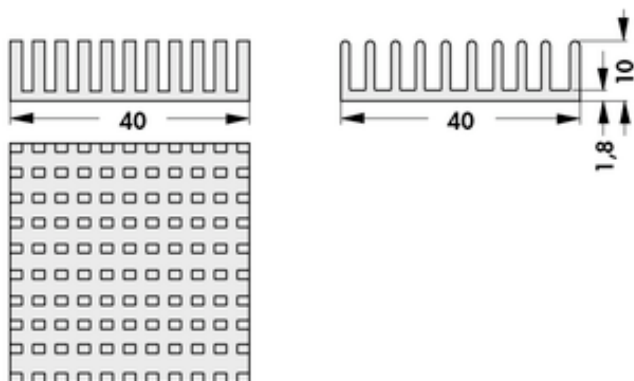
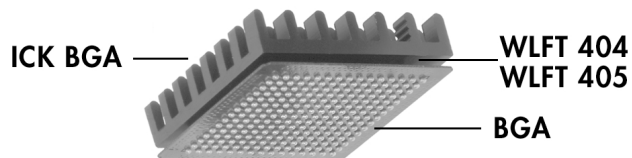


Heatsinks for BGAs / **ICK BGA 40 x 40 x 10**



40 x 40 x 10 mm, for IC design BGA and others

Parameters of article **ICK BGA 40 x 40 x 10**

R_{th} [K/W]	i 13.8
dissipation loss [W]	i 4.4
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	40
height [mm]	10
plate thickness [mm]	1.8
length on stock [mm]	40
surface treatment	black anodised

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 40 x 40**

Thermally conductive foil both sides adhesive / **WLFT 405 40 x 40**